



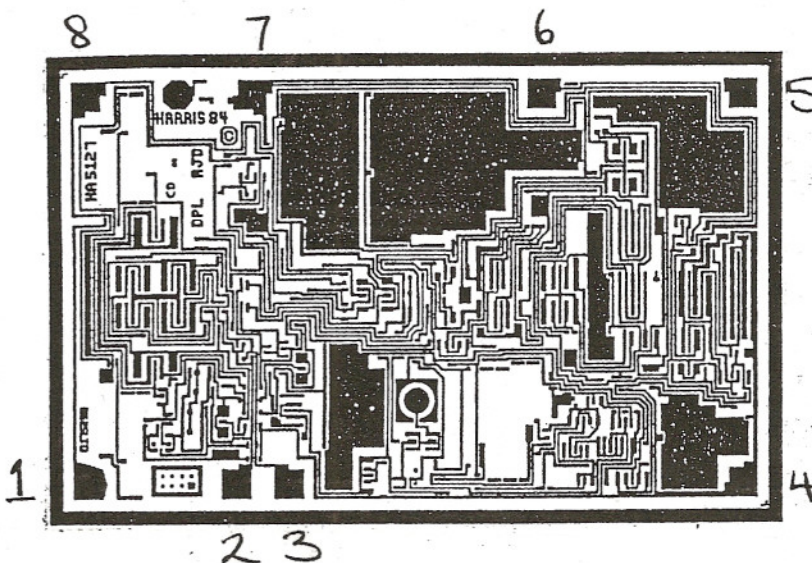
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

Pad Function

1	BAL
2	-IN
3	+IN
4	V-
5	NC
6	OUT
7	V+
8	BAL



NOTES: Chip back may be connected to V- or may be left floating.

NC = No Connect

Topside Metal: Al/ 12kA thick

Backside: Si

Backside Potential: V-

Mask Ref: -

Bond Pads: .004" min.

APPROVED BY: CD

MFG: Harris

DIE SIZE: .104" x .065"

THICKNESS: .019"

DATE: 8/5/02

P/N: HAO5127-6